



Part Number : 878030132

Series Number : 87803


Product Category : Memory Module
Connectors

Product Description : 1.00mm Pitch DDR2
DIMM Socket, Through Hole, 25° Angle,
0.76µm Gold (Au), 3.18mm Solder tail, 240
Circuits, Natural (Off White) Latch, Lead-Free
Status : Obsolete

Documents & Resources

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	
EU ELV	Not Relevant
Low-Halogen Status	Not Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2024)4144-DC (27 June 2024)
EU RoHS	Compliant per EU 2015/863

Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

EU RoHS Certificate of Compliance

Part Details

General

Status	Obsolete
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Series	87803
Description	1.00mm Pitch DDR2 DIMM Socket, Through Hole, 25° Angle, 0.76µm Gold (Au), 3.18mm Solder tail, 240 Circuits, Natural (Off White) Latch, Lead-Free
Comments	Lubricant at the contact
Component Type	Socket
JEDEC Outline	MO-237
Product Family	Memory Module Sockets
Product Name	DDR2 DIMM
UPC	822350956529

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	0.5A
Voltage Key	1.8V, Center
Voltage - Maximum	30V AC (RMS)/DC

Physical

Circuits (Loaded)	240
Circuits (maximum)	240
Durability (mating cycles max)	25
Entry Angle	25° Angle
Flammability	94V-0
Housing Color	Black
Keying to Mating Part	Yes
Latch Color	Natural (Off-White)
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic

Net Weight	11.409/g
Packaging Type	Tray
PC Tail Length	3.18mm
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness - Recommended	2.36mm
Pitch - Mating Interface	1.00mm
Plating min - Mating	0.762μm
Plating min - Termination	2.540μm
Temperature Range - Operating	-55° to +85°C
Termination Interface Style	Through Hole

Solder Process Data

Max-Duration	5
Lead-Free Process Capability	SMC&WAVE
Max-Cycle	2
Max-Temp	260